

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10791192
<b>Filing Date:</b>	02-Mar-2004
<b>Title of Invention:</b>	TWO-STAGE TRANSFER MOLDING DEVICE TO ENCAPSULATE MMC MODULE
<b>First Named Inventor/Applicant Name:</b>	Todd O. Bolken
<b>Filer:</b>	James R. Duzan/Deidra Pfeil
<b>Attorney Docket Number:</b>	2269-4794.4US (01-0185.04)

Filed as Large Entity

### Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appl issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				1700